

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Standard Plastic and Ceramic 300-mil DIPs
- Dependable Texas Instruments Quality and Reliability

TYPE	TYPICAL AVERAGE	TYPICAL
	PROPAGATION DELAY TIME	TOTAL POWER DISSIPATION
'86	14 ns	150 mW
'LS86A	10 ns	30.5 mW
'S86	7 ns	250 mW

### description

These devices contain four independent 2-input Exclusive-OR gates. They perform the Boolean functions  $Y = A \oplus B = \bar{A}B + A\bar{B}$  in positive logic.

A common application is as a true/complement element. If one of the inputs is low, the other input will be reproduced in true form at the output. If one of the inputs is high, the signal on the other input will be reproduced inverted at the output.

The SN5486, 54LS86A, and the SN54S86 are characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN7486, SN74LS86A, and the SN74S86 are characterized for operation from  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ .

### exclusive-OR logic

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.



These are five equivalent Exclusive-OR symbols valid for an '86 or 'LS86A gate in positive logic; negation may be shown at any two ports.

#### LOGIC IDENTITY ELEMENT



The output is active (low) if all inputs stand at the same logic level (i.e.,  $A=B$ ).

#### EXCLUSIVE-OR

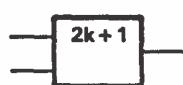


#### EVEN-PARITY



The output is active (low) if an even number of inputs (i.e., 0 or 2) are active.

#### ODD-PARITY ELEMENT



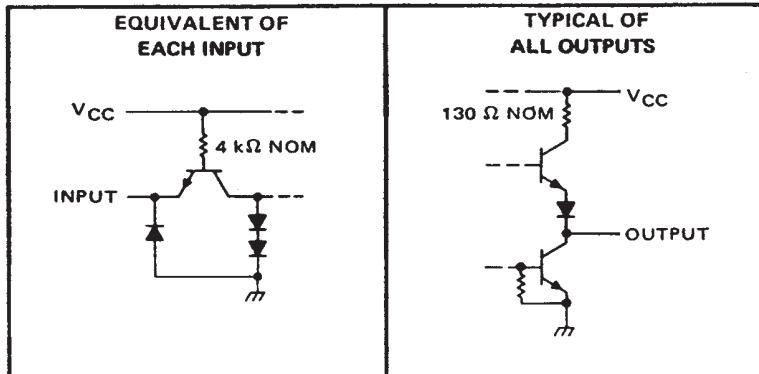
The output is active (high) if an odd number of inputs (i.e., only 1 of the 2) are active.

**SN5486, SN54LS86A, SN54S86  
SN7486, SN74LS86A, SN74S86  
QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES**

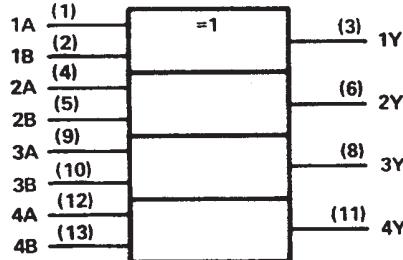
SDLS124 – DECEMBER 1972 – REVISED MARCH 1988

**schematics of inputs and outputs**

'86

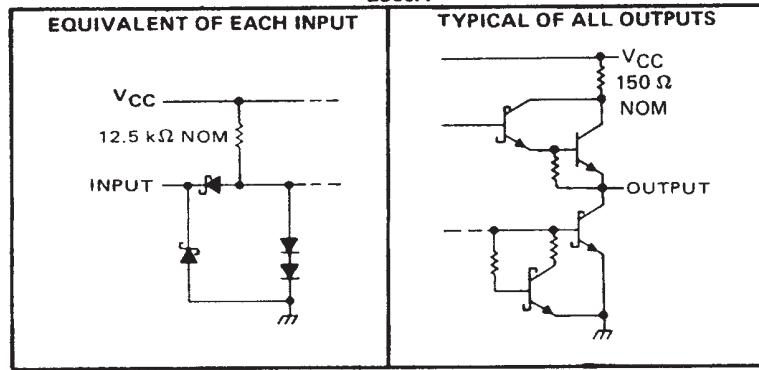


**logic symbol†**



†This symbol is in accordance with  
ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.  
Pin numbers shown are for D, J, N, and W packages.

'LS86A

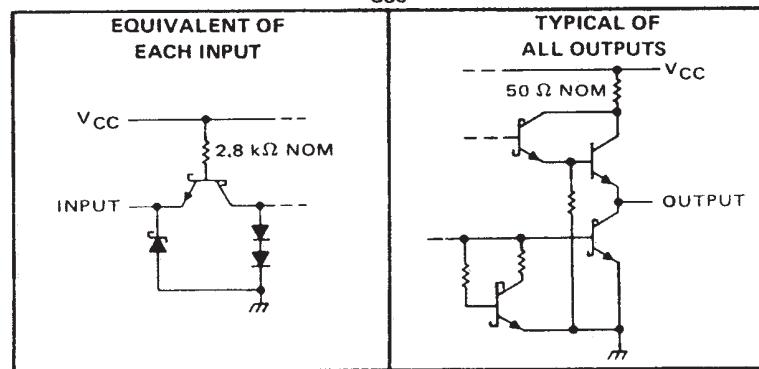


**FUNCTION TABLE**

INPUTS	OUTPUT	
	A	B
L	L	L
L	H	H
H	L	H
H	H	L

H = high level, L = low level

'S86













Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SNJ54LS86AW	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS86AW	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S86FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S86FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S86J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S86J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S86W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S86W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

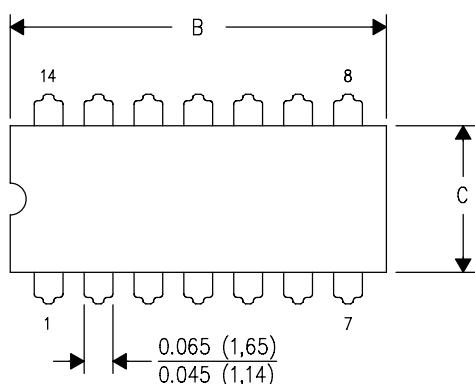
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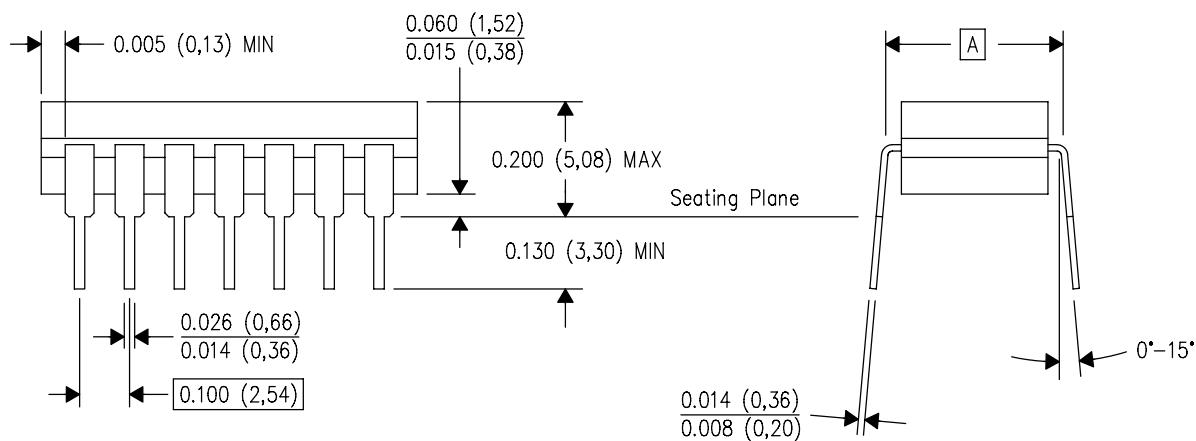
J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



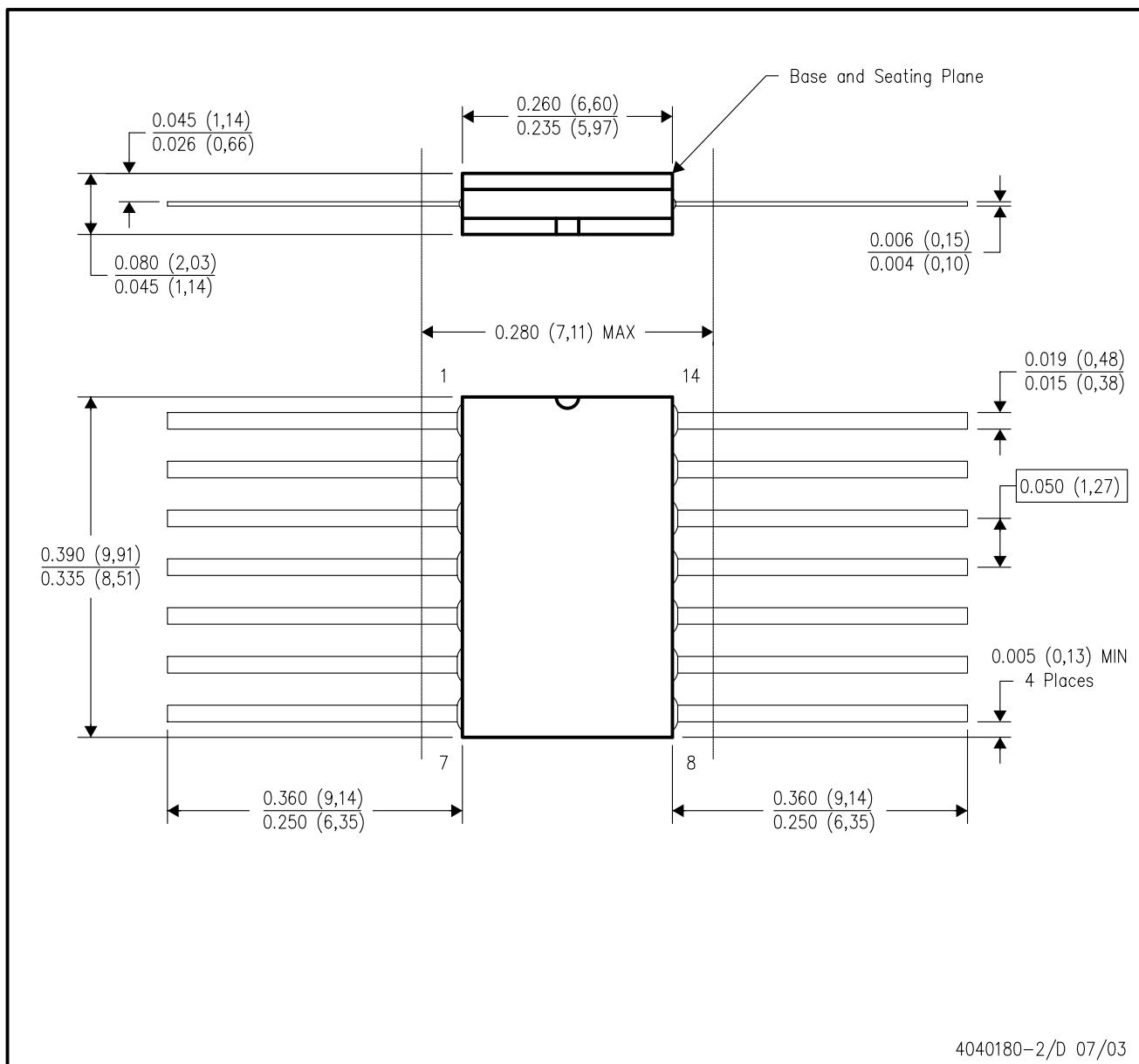
4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## MECHANICAL DATA

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

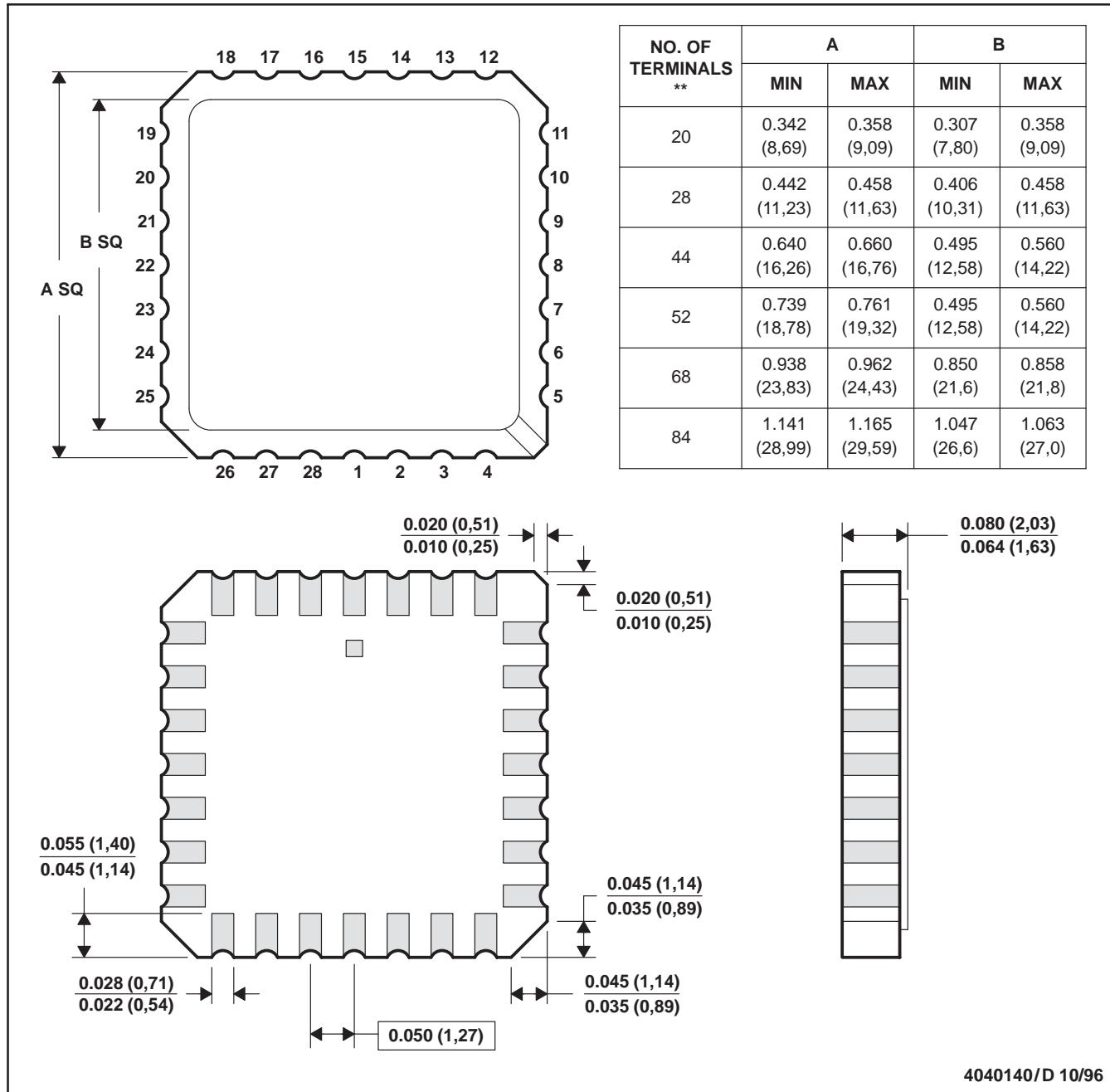
# MECHANICAL DATA

MLCC006B – OCTOBER 1996

**FK (S-CQCC-N\*\*)**

28 TERMINAL SHOWN

**LEADLESS CERAMIC CHIP CARRIER**



4040140/D 10/96

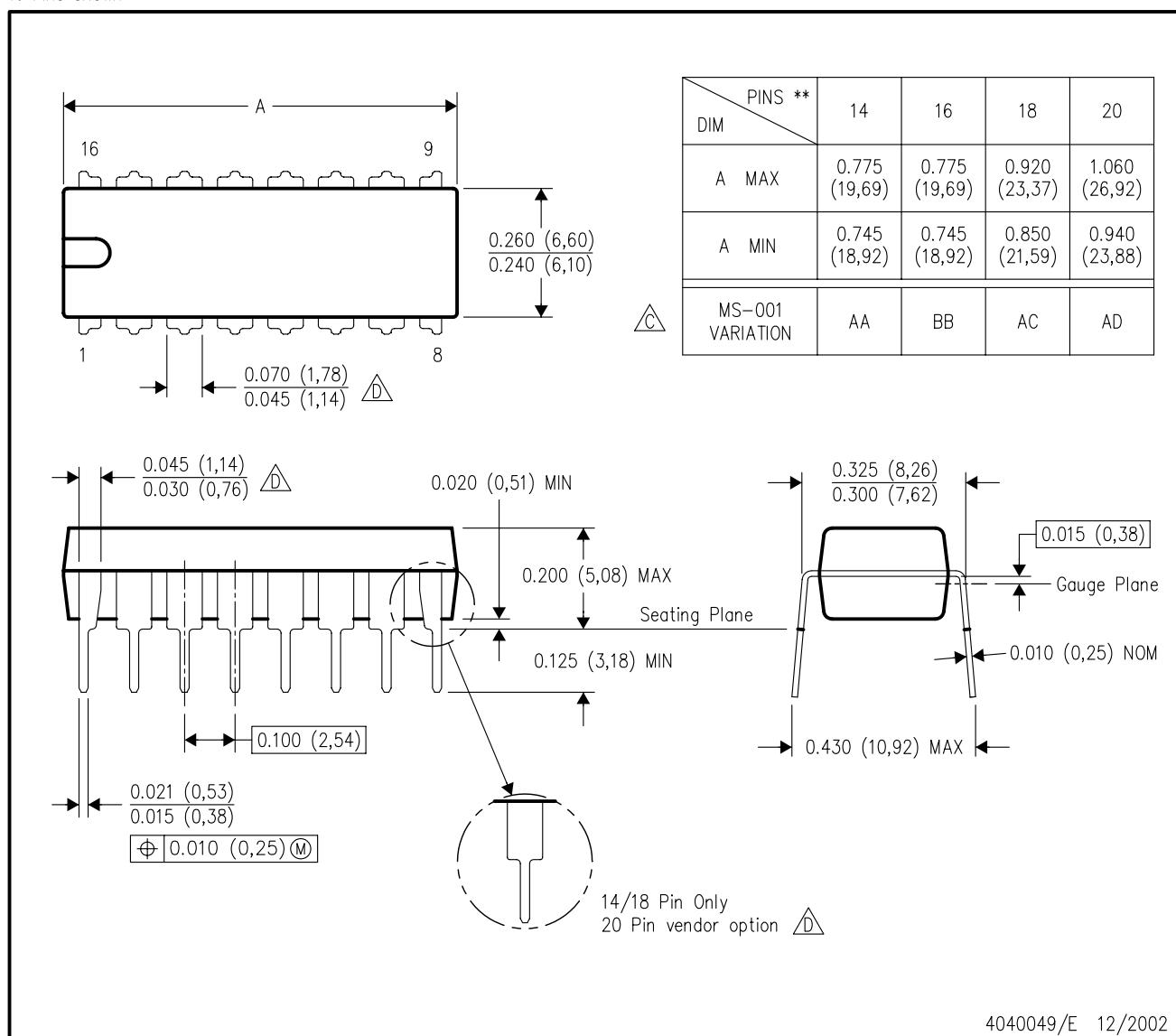
- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - The terminals are gold plated.
  - Falls within JEDEC MS-004

## MECHANICAL DATA

N (R-PDIP-T\*\*)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



4040049/E 12/2002

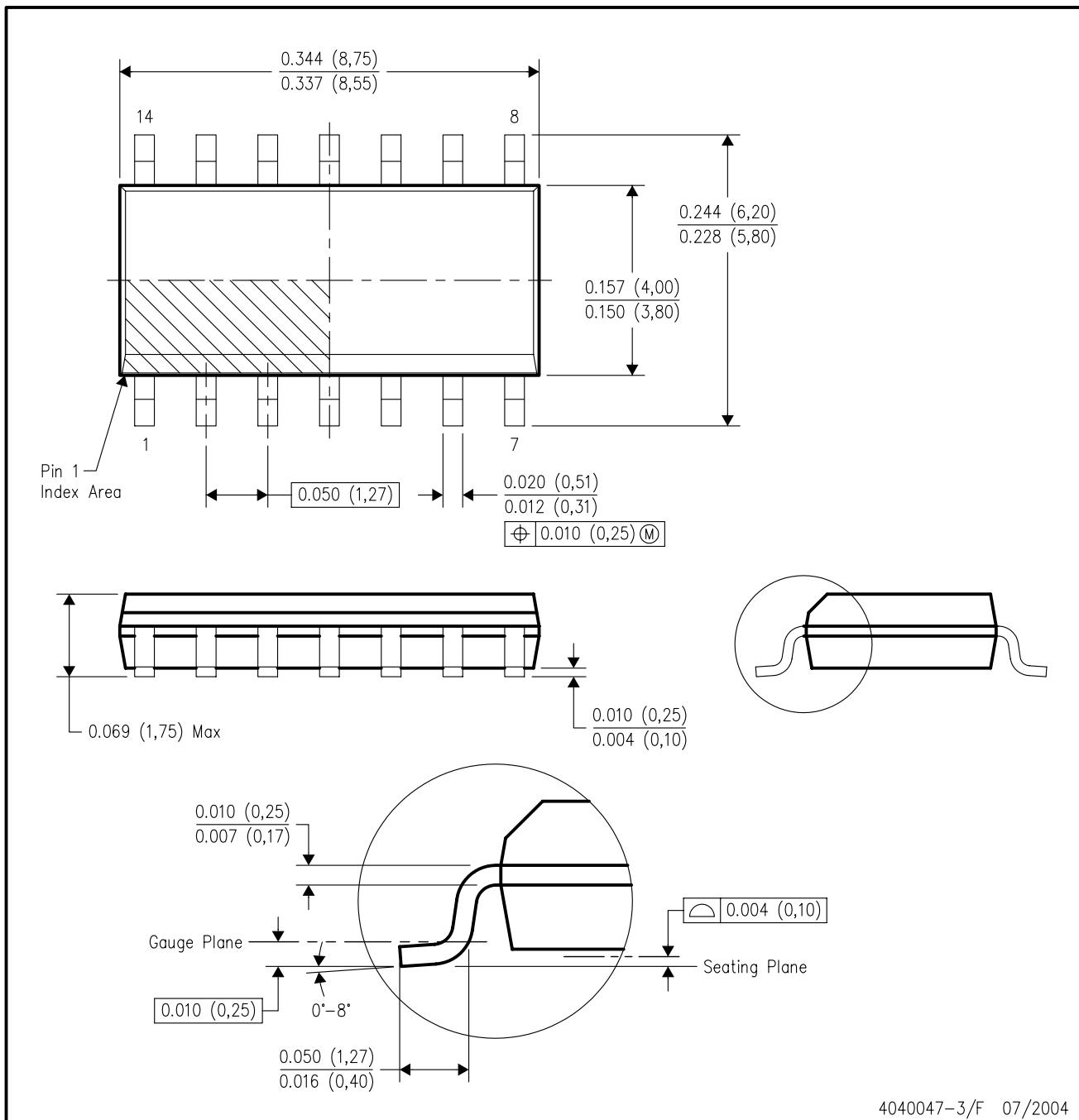
NOTES: A. All linear dimensions are in inches (millimeters).  
B. This drawing is subject to change without notice.

$\triangleleft C$  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).  
 $\triangleleft D$  The 20 pin end lead shoulder width is a vendor option, either half or full width.

## MECHANICAL DATA

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



4040047-3/F 07/2004

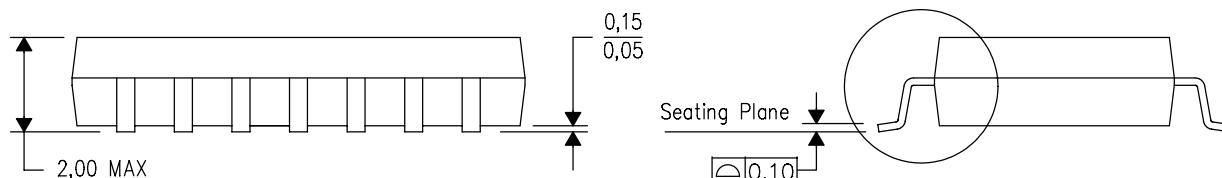
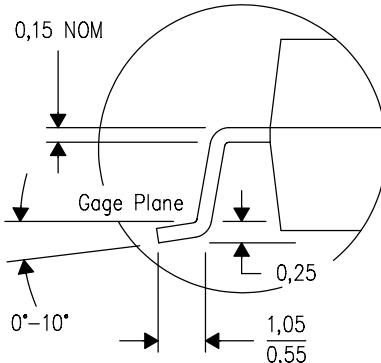
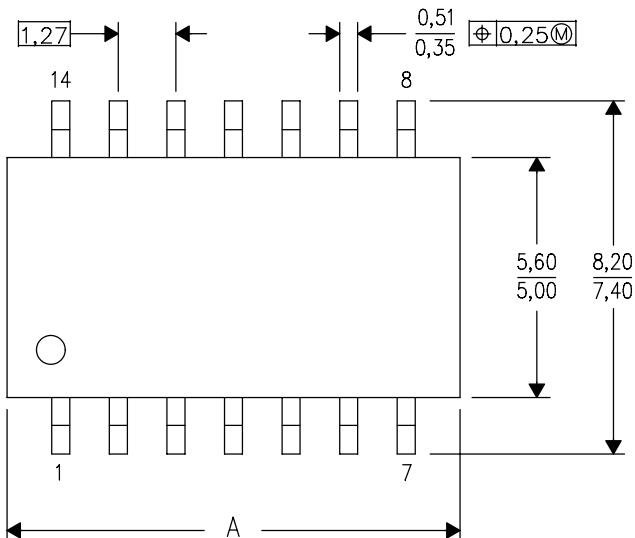
- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - Falls within JEDEC MS-012 variation AB.

## MECHANICAL DATA

NS (R-PDSO-G\*\*)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



PINS ** DIM	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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